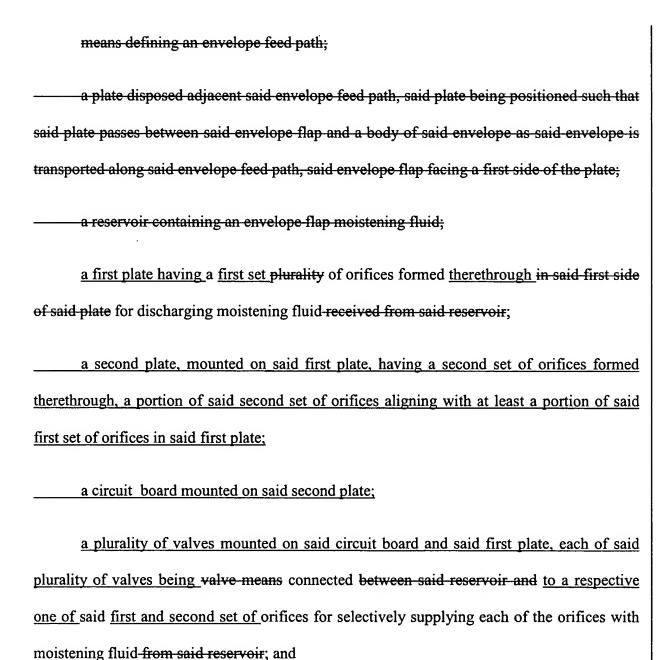
Amendments to the Claims:

1. (Currently Amended) A device for moistening an envelope flap of an envelope, comprising:



Amendment dated November 23, 2004

Response to Office Action dated Sept. 9, 2004

flap sensing means mounted on said circuit board disposed adjacent said envelope

feed path for sensing an edge portion of said envelope flap, and operatively connected to said

plurality of valves valve means for supplying signals to said plurality of valves valve means

for selectively actuating each of said plurality of valves valve means to selectively supply

moistening fluid to said first and second sets of orifices in response to the sensing of the edge

portion of said envelope flap.

2. (Currently Amended) The device according to claim 1, wherein said first set of orifices

are arranged in a first substantially linear array.

3. (Currently Amended) The device according to claim 2, <u>further comprising wherein</u>:

a plurality of fluid paths formed in said first and second plates, the valve means

includes a plurality of valves, each of said plurality of valves controlling a respective fluid

path, each fluid path in fluid communication with at least one of said first and second set of

orifices,; and

wherein the sensing means includes a plurality of sensors arranged in a second

substantially linear array that is parallel to the first linear array and positioned adjacent the

envelope feed path-upstream relative to the first linear array, the sensors being operative to

control said valves, the plurality of sensors being like in number to the plurality of valves.

4. (Original) The device according to claim 3, wherein the plurality of valves includes at

least six valves and the plurality of sensors includes at least six sensors.

Page 3 of 9

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Amendment dated November 23, 2004

Response to Office Action dated Sept. 9, 2004

5. (Currently Amended) The device according to claim 3, wherein each fluid path is in

fluid communication with a respective pair of said first and second set of orifices.

6-15. Cancelled.

16. (Original) An envelope flap moistening assembly, comprising:

a first horizontal plate having a plurality of orifices formed therethrough;

a second horizontal plate mounted on the first horizontal plate;

a horizontal circuit board mounted on the second horizontal plate;

a plurality of sensors mounted on an underside of said circuit board; and

a plurality of valves, each mounted on said circuit board or mounted on said first

horizontal plate.

17. (Original) The envelope flap moistening assembly according to claim 16, further

comprising circuit means on the circuit board operatively connected to the sensors and to the

valves for selectively actuating the valves in response to the sensors sensing an edge of an

envelope flap.

18. (Original) The envelope flap moistening assembly according to claim 16, wherein:

the orifices are arranged in a first substantially linear array; and

the sensors are arranged in a second substantially linear array, the second array

parallel to and horizontally offset from the first array.

Amendment dated November 23, 2004

Response to Office Action dated Sept. 9, 2004

19. (Original) The envelope flap moistening assembly according to claim 18, wherein the

second array is vertically offset from the first array.

20. (Original) The envelope flap moistening assembly according to claim 16, wherein the

plurality of valves includes at least six valves.

21. (Original) The envelope flap moistening assembly according to claim 16, wherein at least

one of the first and second plates has a plurality of fluid channels formed therealong, each of

the fluid channels controlled by a respective one of the valves and in fluid communication

with at least a respective one of the orifices.

22. (Original) The envelope flap moistening assembly according to claim 21, wherein both of

the first and second plates have a respective plurality of the fluid channels formed therealong.

23. (Original) The envelope flap moistening assembly according to claim 22, wherein the

first and second plates and the circuit board are sandwiched together, with a top surface of the

first plate in contact with a bottom surface of the second plate, and a top surface of the second

plate in contact with a bottom surface of the circuit board.

24. (Original) The envelope flap moistening assembly according to claim 16, wherein some

of the valves are mounted on the circuit board and some of the valves are mounted on the first

horizontal plate.

25. (Currently Amended) A mailing machine comprising:

an envelope feed path;

Page 5 of 9

Serial No.: 10/660,240 Amendment dated November 23, 2004

Response to Office Action dated Sept. 9, 2004

a reservoir for holding an envelope flap moistening fluid;

a moistening device disposed along said feed path such that said moistening device passes between an envelope flap and a body of an envelope as said envelope is transported along said envelope feed path, said moistening device comprising:

a plate positioned such that said plate passes between an envelope flap and a body of an envelope as said envelope is transported along said envelope feed path, said envelope flap facing a first side of the plate;

a reservoir-containing an envelope flap moistening fluid;

a first plate having a first set plurality of orifices formed therethrough in said first side of said plate for discharging moistening fluid received from said reservoir, said first plate being positioned substantially horizontal with respect to said envelope feed path;

a second plate, mounted on said first plate, having a second set of orifices formed therethrough, a portion of said second set of orifices aligning with at least a portion of said first set of orifices in said first plate;

a circuit board mounted on said second plate;

a plurality of valves mounted on said circuit board and said first plate, each of said plurality of valves being at least one valve connected between said reservoir and a respective one of said first and second set of orifices for selectively supplying each of the orifices with moistening fluid from said reservoir; and

Amendment dated November 23, 2004

Response to Office Action dated Sept. 9, 2004

a flap sensing circuit <u>mounted on said circuit board and</u> disposed adjacent said envelope feed path to sense an edge portion of said envelope flap, and operatively connected to said <u>plurality of valves at least one valve</u> for supplying signals to said <u>plurality of valves at least one valve</u> for selectively actuating <u>each of said plurality of valves at least one valve</u> to selectively supply moistening fluid to said <u>first and second sets of orifices in response to the sensing of the edge portion of said envelope flap.</u>

- 26. (Currently Amended) The mailing machine according to claim 25, wherein said plate is substantially horizontal, and said moistening fluid is discharged in a downward direction.
- 27. (Currently Amended) The mailing machine according to claim 25, wherein an angle formed by said envelope flap and said body of said envelope to allow said moistening device plate to pass between said envelope flap and said body of said envelope is approximately 30° or less.